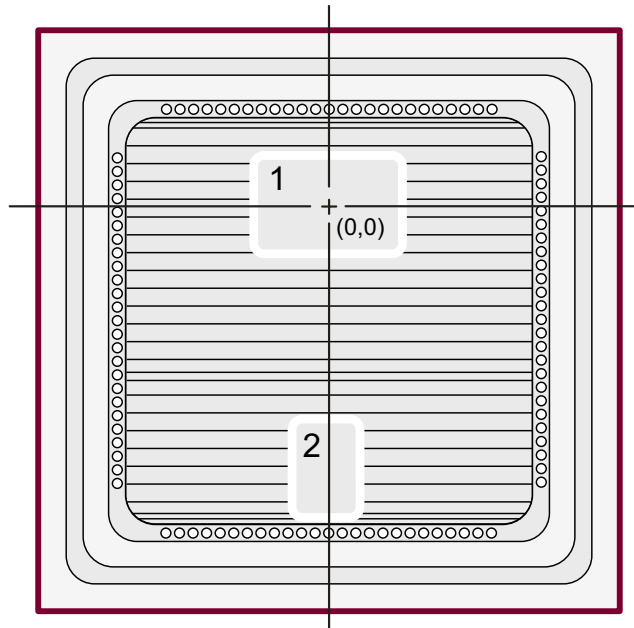


Pad Layout



Backside: Drain

Die Specifications

Device	Die Dimensions			Back Side Metal	Back Side	Bonding Pad Material
	Length ¹ (mils)	Width ¹ (mils)	Thickness (mils)			
TN0110	37	37	11 ± 1.5	Au	Drain	Al/Cu/Si

Bonding Pad Description

Pad #	Function	x Position ² (mils)	y Position ² (mils)	x Size (mils)	y Size (mils)
1	Source	0	0	9.0	6.3
2	Gate	0	-17.1	4.3	5.1

Notes:

1. Maximum values.
2. Position referenced to center of pad.

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